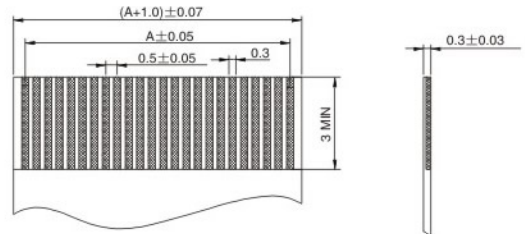
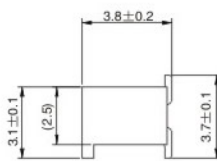
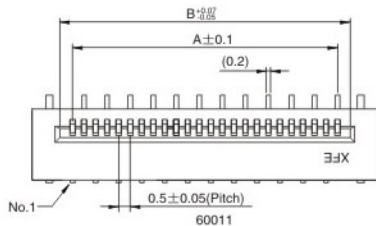
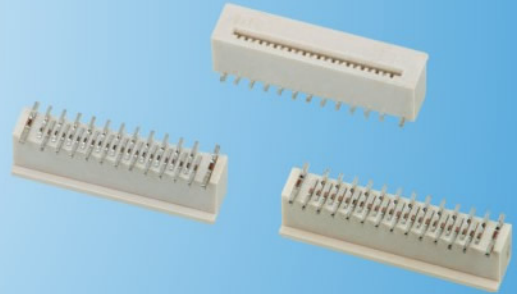


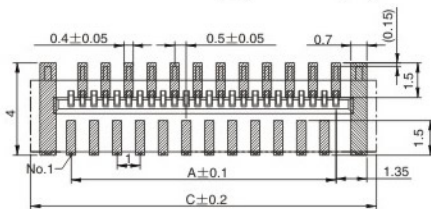
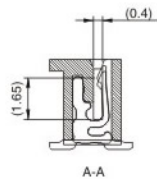
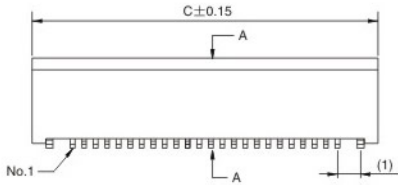
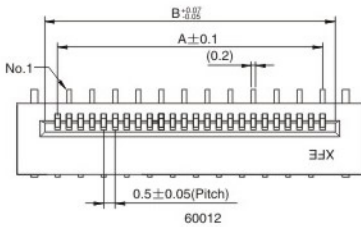
## 0.5D Series-0.5mm FPC CONN. NON-ZIF Straight SMT, H=3.8

Current Rating: 0.5AMP  
 Insulation Resistance:  $\geq 500M\Omega$   
 Contact Resistance:  $\leq 0.03\Omega$   
 Withstanding Voltage: 500V,AC/Minute  
 Voltage Rating: 50v, AC,DC  
 Operation Temperature: -25°C~85°C

Material:  
 Contact: Copper Alloy  
 Plating: Sn over Ni  
 Insulator: High Temperature Thermoplastic(UL94V-0)

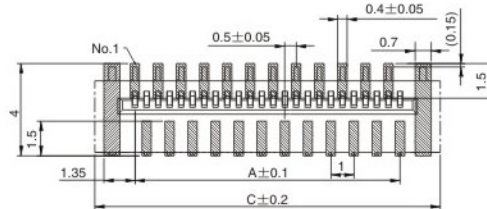


APPLICABLE FPC



RECOMMENDED PCB LAYOUT

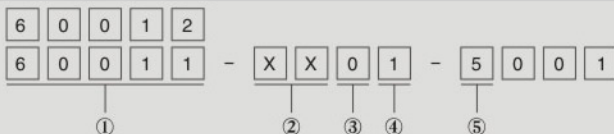
60011



RECOMMENDED PCB LAYOUT

60012

CKT	Dim A	Dim B	Dim C
8	3.5	4.56	7
10	4.5	5.56	8
12	5.5	6.56	9
14	6.5	7.56	10
16	7.5	8.56	11
20	9.5	10.56	13
22	10.5	11.56	14
24	11.5	12.56	15
25	12	13.06	15.5
26	12.5	13.56	16



- ① Series No.
- ② NO. of Contact
- ③ Packing Option (0=Reel, 1=Tube, 2=Tray, 3=Bag)
- ④ Plating: 1=BRIGHT-TIN, 80 μ"Min Over Ni, 30 μ"Min...
- ⑤ Lead Free & HF ( 1&2=Lead Free, 5&6=Halogen-free)